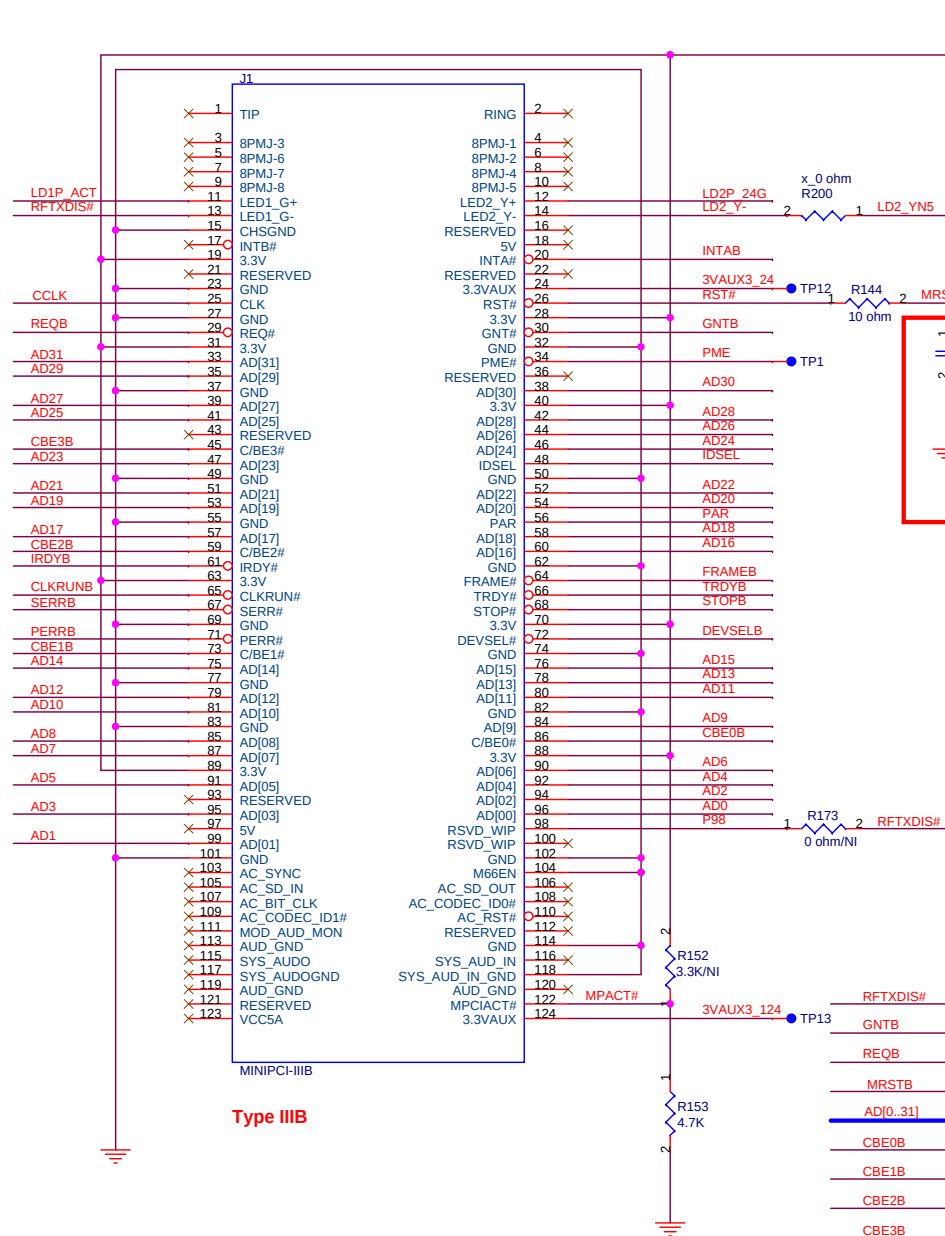
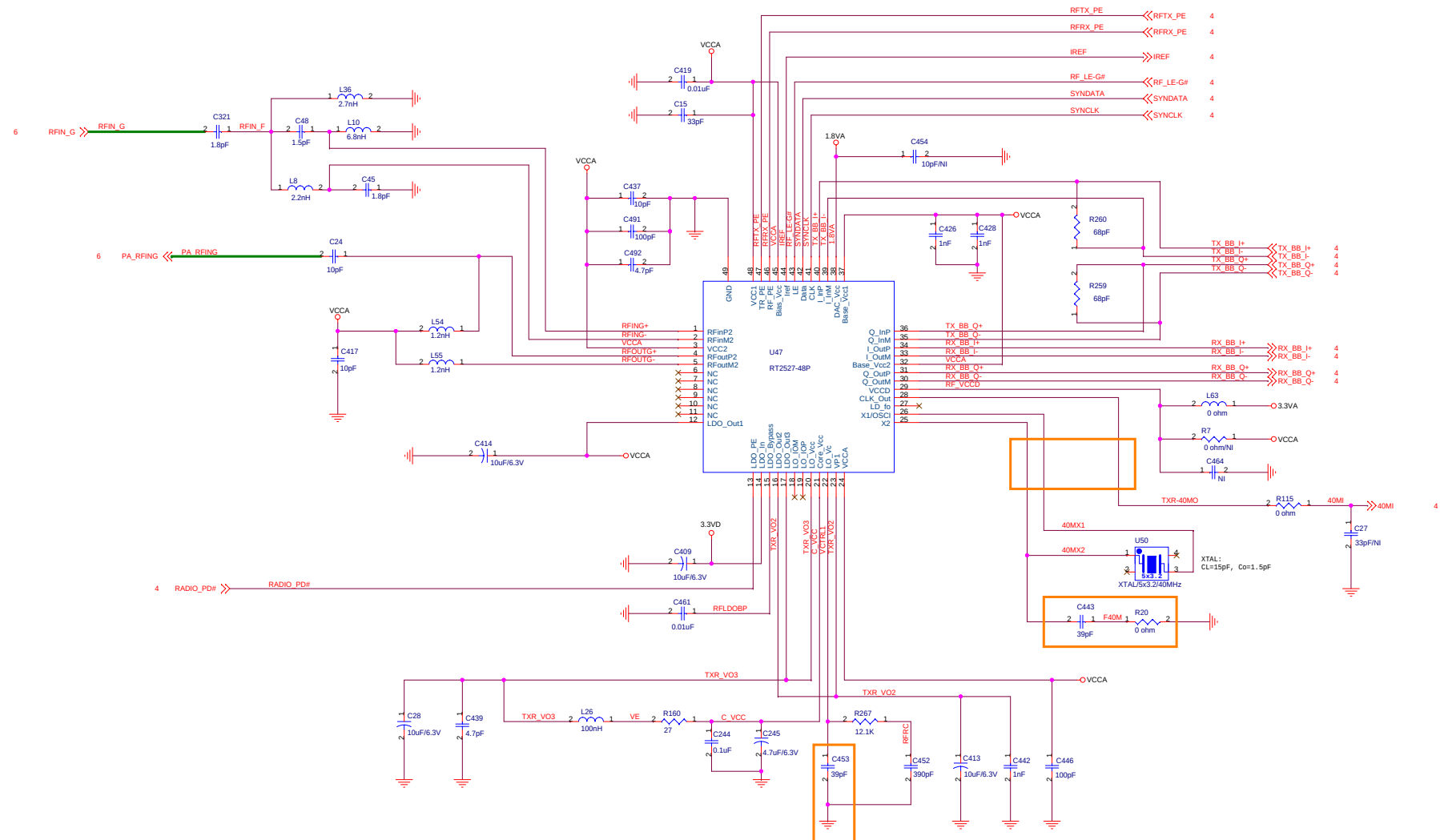
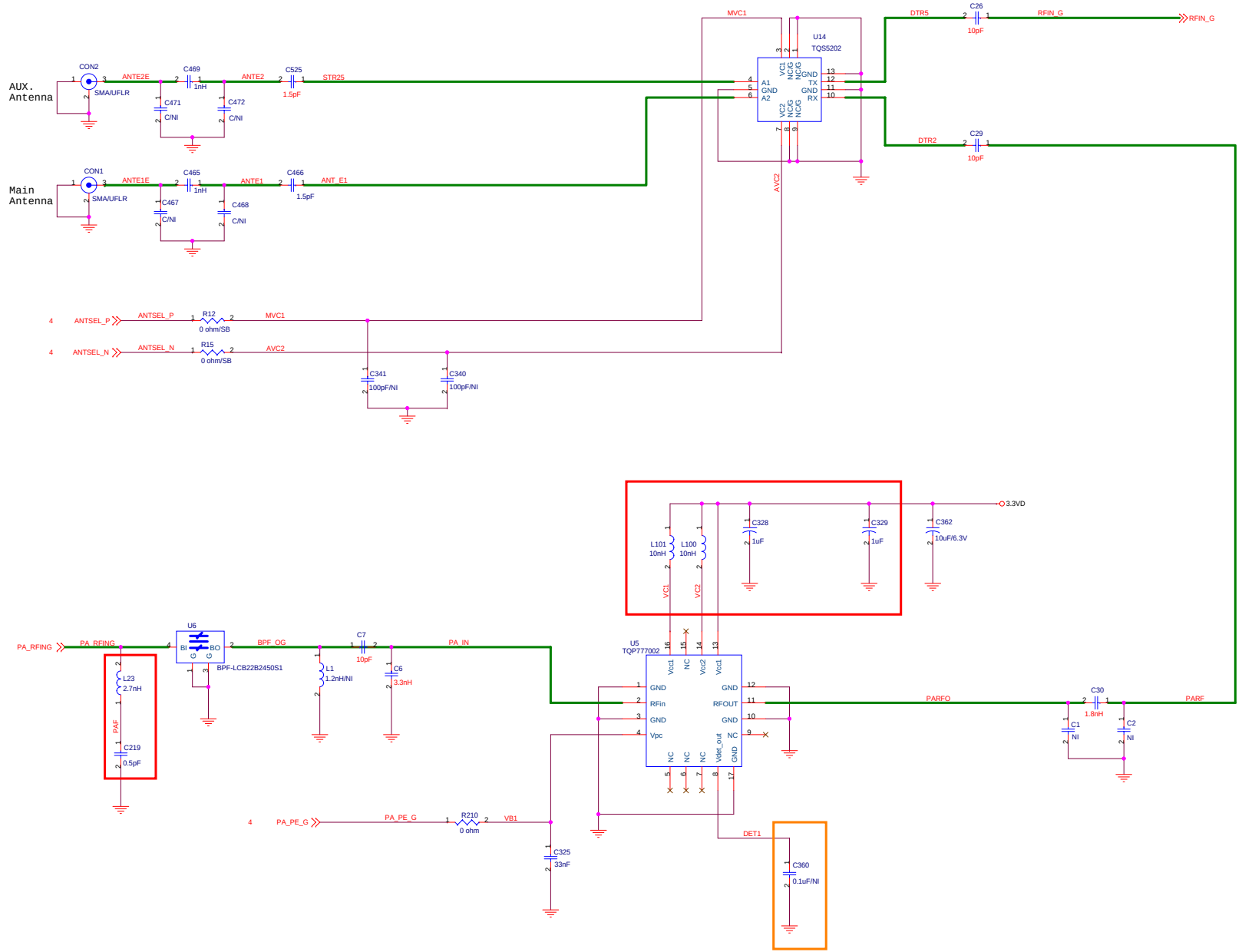


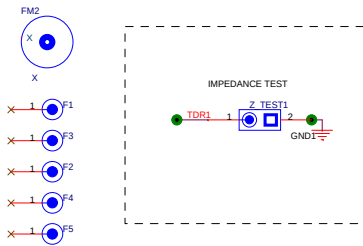
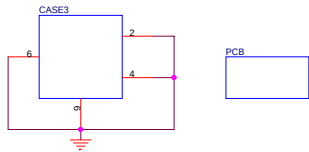


RFTXDIS#	>>RFTXDIS#	4	LD1P_ACT	<<LD1P_ACT	4
GNTB	>>GNTB	4	LD2P_24G	<<LD2P_24G	4
REQB	<<REQB	4	LD2_YN5	<<LD2_YN5	4
MRSTB	<<MRSTB	4	INTAB	<<INTAB	4
AD[0..31]	>>AD[0..31]	4	IDSEL	>>IDSEL	4
CBE0B	>>CBE0B	4	STOPB	>>STOPB	4
CBE1B	>>CBE1B	4	DEVSELB	>>DEVSELB	4
CBE2B	>>CBE2B	4	PERRB	>>PERRB	4
CBE3B	>>CBE3B	4	FRAMEB	>>FRAMEB	4
PAR	>>PAR	4	SERRB	<<SERRB	4
TRDYB	>>TRDYB	4	CCLK	>>CCLK	4
IRDYB	>>IRDYB	4	CLKRUNB	>>CLKRUNB	4









Mini-PCI PCB Layer Stack-Up		Material	Thickness (Finished Total Thickness: 39+-4 mil)
	Solder mask		0.4 mil
(TOP)	LAYER 1	1/2 OZ Cu + Gold Plating	1.6 mil
		PrePeg FR4 (1506)	12 mil
(Ground)	LAYER 2	1 OZ Cu	1.6 mil
		Core FR4	7 mil
(Power)	LAYER 3	1 OZ Cu	1.6 mil
		PrePeg FR4 (1506)	12 mil
(Bottom)	LAYER 4	1/2 OZ Cu + Gold Plating	1.6 mil
	Solder mask		0.4 mil
Dielectric Constant: 4.3			
50-ohm Co-Planar Waveguide: 16 mil Line Width, 10 mil Gap Width			